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N-Channel 40 V (D-S) MOSFET

| PRODUCT SUMMARY | | | | | |
|---------------------|-------------------------------|---------------------------------|-----------------------|--|--|
| V _{DS} (V) | $R_{DS(on)}(m\Omega)(Typ.)$ | I _D (A) ^a | Q _g (Typ.) | | |
| 40 | 9.8 at V _{GS} = 10 V | 35 | 43 nC | | |
| 40 | 11 at V _{GS} = 4.5 V | 35 | 43 110 | | |

FEATURES

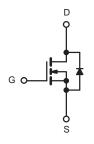
- DT-Trench Power MOSFET
- $\bullet\,$ 100 % R_g and UIS Tested
- Fast switching

APPLICATIONS

- Networking
- · Load Switch
- · LED applications

DFN3X3-8L Pin Configuration





N-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted) | | | | | |
|---|-----------------------------------|------------------|------|----|--|
| PARAMETER | SYMBOL | LIMIT | UNIT | | |
| Drain-Source Voltage | V _{DS} | 40 | V | | |
| Gate-Source Voltage | | V _{GS} | ± 20 | V | |
| Continuous Drain Current (T _{.I} = 175 °C) ^a | T _C = 25 °C | | 35 | А | |
| Continuous Diam Current (1) = 175 C) | T _C = 100 °C | - I _D | 28 | | |
| Pulsed Drain Current ^b | I _{DM} | 140 | | | |
| Single Avalanche Energy | E _{AS} | 75 | mJ | | |
| Maximum Power Dissipation ^c | T _C = 25 °C | P _D | 32 | W | |
| iviaximum rower bissipation | T _C = 100 °C | F _D | 15.9 | VV | |
| Operating Junction and Storage Temperature Ra | T _J , T _{stg} | - 55 to + 175 | °C | | |

7 D

| THERMAL RESISTANCE RATINGS | | | | | |
|--|-------------------|-------|------|--|--|
| PARAMETER | SYMBOL | LIMIT | UNIT | | |
| Junction-to-Ambient (PCB Mount) ^d | R _{thJA} | 45 | °C/W | | |
| Junction-to-Case (Drain) | R _{thJC} | 4.7 | | | |

Notes

- a. Calculated continuous current based on maximum allowablejunction temperature.
- b. Repetitive rating; pulse width limited by max. junction temperature.
- c. Pd is based on max. junction temperature, using junction-case thermal resistance.
- d. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with Ta=25 °C.



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| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNIT | |
|---|---|--|------|------|-------|------|--|
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | V _{GS} = 0 V, I _D = 250 μA | 40 | - | - | V | |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} = V _{GS} , I _D = 250 μA | 1 | - | 3 | V | |
| Gate-Body Leakage | I _{GSS} | | | - | ± 100 | nA | |
| Zero Gate Voltage Drain Current | | V _{DS} = 40 V, V _{GS} = 0 V | - | - | 1 | | |
| Zero Gate Voltage Drain Current | I _{DSS} | Vps = 32 V, Vgs = 0 V, Tj = 55 °C | - | - | 100 | μA | |
| On-State Drain Current ^a | I _{D(on)} | V _{DS} ≥ 5 V, V _{GS} = 10 V | 35 | - | - | Α | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | V _{GS} = 10 V, I _D = 10 A | - | 9.8 | 11 | mΩ | |
| | NDS(on) | V _{GS} = 4.5 V, I _D = 8 A | - | 11 | 13 | | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = 5 V, I _D = 10 A | - | 50 | - | S | |
| Dynamic ^b | | | | | | | |
| Input Capacitance | C _{iss} | | - | 2280 | - | pF | |
| Output Capacitance | C _{oss} | $V_{GS} = 0 \text{ V}, V_{DS} = 20 \text{ V}, f = 1 \text{ MHz}$ | - | 168 | - | | |
| Reverse Transfer Capacitance | C _{rss} | | - | 147 | - | | |
| Total Gate Charge ^c | Q_g | | - | 43 | - | | |
| Gate-Source Charge ^c | Q_{gs} | $V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$ | - | 4 | - | nC | |
| Gate-Drain Charge ^c | Q_{gd} | | - | 6.6 | - | | |
| Gate Resistance | R_g | f = 1 MHz | - | 3.3 | - | Ω | |
| Turn-On Delay Time ^c | t _{d(on)} | | - | 5.5 | - | | |
| Rise Time ^c | t _r | $V_{DD} = 20 \text{ V}, I_D = 10 \text{ A}, R_g = 1 \Omega$ | - | 8 | - | no | |
| Turn-Off Delay Time ^c | t _{d(off)} | V _{GS} = 10 V | - | 18 | - | ns | |
| Fall Time ^c | t _f | | - | 10 | - | | |
| Drain-Source Body Diode Ratings and | Characterist | ics ^b (T _C = 25 °C) | | | | | |
| Continuous Source-Drain Diode Current | Is | T _C = 25 °C | - | - | 35 | А | |
| Pulsed Current | I _{SM} | | - | - | 140 | Α | |
| Forward Voltage ^a | V_{SD} | I _F = 1 A, V _{GS} = 0 V | - | - | 1.2 | V | |
| ody diode reverse recovery time t _{rr} | | L = 10 A di/dt = 100 A/::a | - | 15 | - | ns | |
| Body diode reverse recovery charge | everse recovery charge Q_{rr} $I_F = 10 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s}$ | | - | 48 | - | nC | |

Notes

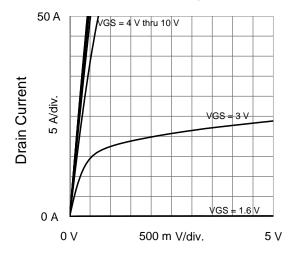
- a. Pulse test; pulse width $\leq 300 \,\mu\text{s}$, duty cycle $\leq 2 \,\%$.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those in dicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

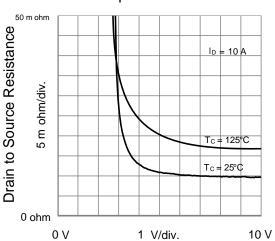




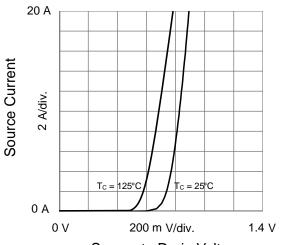
TYPICAL CHARAC TERISTICS (25 °C, unless otherwise noted)



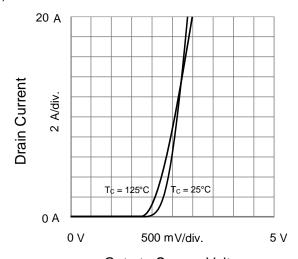
Drain to Source Voltage Output Characteristics



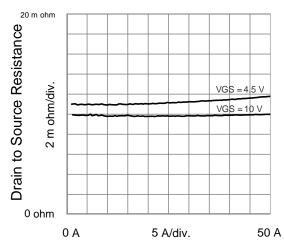
Gate to Source Voltage
Drain to Source Resistance vs. Gate to Source Voltage



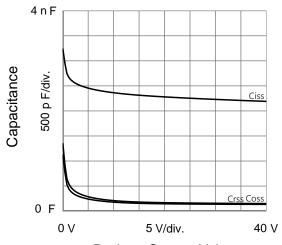
Source to Drain Voltage Body Diode Forward Characteristics



Gate to Source Voltage Transfer Characteristics



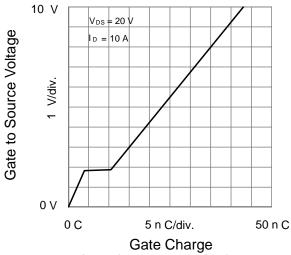
Drain Current

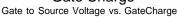


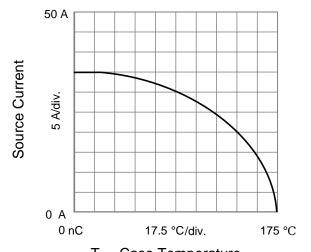
Drain to Source Voltage Capacitances



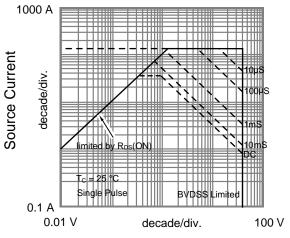
TYPICAL CHARAC TERISTICS (25 °C, unless otherwise noted)



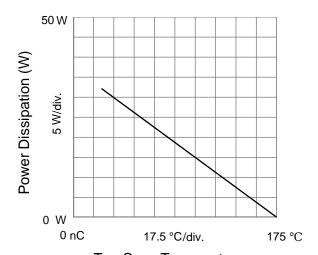




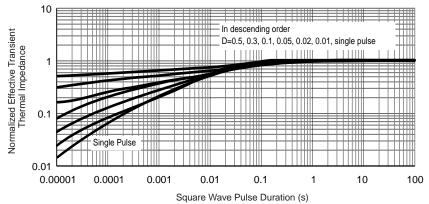
T_A - Case Temperature



Source to Drain Voltage Safe Operating Area, Junction-to-Case



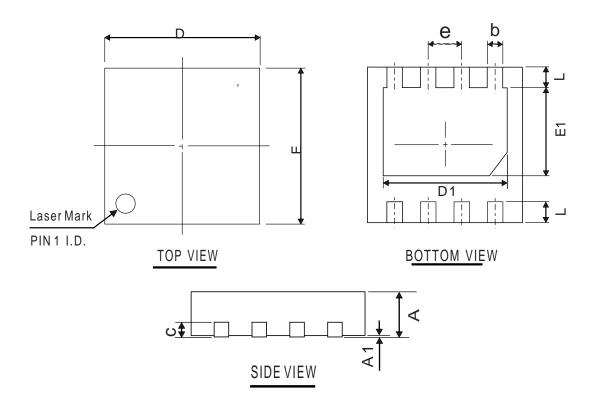
T_C - Case Temperature



Normalized Thermal Transient Impedance, Junction-to-Case



DFN3*3-8L PACKAGEOUTLINE



COMMON DIMENSIONS (UNITS OF MEASURE=mm)

| SYMBOL | MIN | NOM | MAX |
|--------|----------|------|------|
| Α | 0.60 | 0.75 | 0.90 |
| A1 | 0.00 | 0.02 | 0.08 |
| b | 0.00 | 0.30 | 0.45 |
| D | 2.85 | 3.00 | 3.15 |
| E | 2.85 | 3.00 | 3.15 |
| D1 | 2.10 | 2.40 | 2.70 |
| E1 | 1.50 | 1.70 | 2.00 |
| L | 0.20 | 0.40 | 0.60 |
| С | 0.203REF | | |
| е | 0.65BSC | | |

OTHER DIMENSIONS

| Α | 0.50 | 0.55 | 0.60 |
|---|------|------|------|
| A | 0.40 | 0.45 | 0.50 |





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